

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Appl. No. : 10/758,487 Confirmation No. 6171  
Applicant(s) : KURODA, Hirofumi  
Filed : 01/15/2004  
TC/A.U. : 2811  
Examiner : Michael J. Feely  
Title : Epoxy Resin Composition and Semiconductor Device Using Thereof

Docket No. : 033036.070  
Customer No. : 25461

MAIL STOP ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450  
Sir:

**TRANSMITTAL LETTER**

Pursuant to Paragraph II of the Notice of Allowance and Fee(s) Due (PTOL-85), applicants submit herewith the Part B - Fee Transmittal form which was inadvertently omitted at the time the issue fee and publication fee were paid. These fees were paid online on June 8, 2006, and the payment of these fees was acknowledged by the PTO in the Electronic Acknowledgement Receipt (a copy of which is attached for convenience).

Respectfully submitted,



By: Robert G. Weilacher, Reg. No. 20,531

Dated: November 17, 2006  
SMITH, GAMBRELL & RUSSELL, LLP  
Suite 3100, Promenade II  
1230 Peachtree Street, N.E.  
Atlanta, Georgia 30309-3592  
Ph: (404) 815-3593  
Fax: (404) 685-6893